

PRODUCTION DATA SHEET

DESCRIPTION

The LX7203 is an integrated identifies appropriate data line for full speed or appliances low speed operation.

The 47 pF capacitor completes the Universal Serial Bus (USB) line high frequency filter and controls the termination device with an EMI filter edge rate of the USB signals The and ESD protection diodes. This LX7203 protects both D+ and D- data device offers a cost effective and lines and the voltage bus from ESD. compact solution for one USB The TVS protection diodes exceed the upstream port. The USB specification requirements of IEC61000-4-2, level 4, requires line termination resistors on 15kV (air discharge) and 8kV (contact both the D+ and D- lines. These discharge). The integrated configuration resistors ensure signal integrity by of the LX7203 minimizes board space matching the cable impedance to that and allows for ideal placement near the of the differential driver. The 1.5 k Ω connector. The LX7203 is ideal for use the in USB hubs, peripherals and portable

IMPORTANT: For the most current data, consult MICROSEMI's website: http://www.microsemi.com

PACKAGE ORDER INFO						
T _J (°C)	Plastic 6-Pin SC70 RoHS Compliant / Pb-free Transition DC: 0450	Package Marking	Tape & Reel Quantity (Reel Size)			
-40 to 125	LX7203-15ISM	31	3K (7inches)			
-40 to 125	LX7203-22ISM	32	or (findles)			

Note: Append the letters "TR" to the part number for Tape & Reel Ordering.

KEY FEATURES

- Small SC70-6L Package
- Bi-directional EMI/RFI low-pass
- Line termination with integrated ESD protection
- Low TVS operating voltage (5.25V)
- Low leakage current
- Integrated single die construction
- Crosses From Semtech STF203

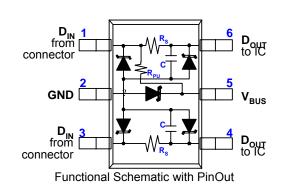
APPLICATIONS

- USB 1.1 and USB 2.0 Full Speed Compliant
- Peripherals
- Computers and Printers
- Mobile phones
- Pagers and PDA's
- **Digital Cameras**

BENEFITS

- Filter response characterized up to 6 GHz
- <2dB insertion loss in the pass band
- >20dB attenuation in the 800-900 MHz range
- >12dB attenuation in the WLAN frequencies of 2.4GHz and 5.0-6.0 GHz

PRODUCT HIGHLIGHT D in D out from to IC connector D in D out from to IC connector Circuit Diagram



Copyright © 2002 Rev. 1.1d, 2005-05-18



PRODUCTION DATA SHEET

ABSOLUTE MAXIMUM RATINGS

Steady State Power	100mW
ESD Air Discharge per IEC61000-4-2	16kV
ESD Contact Discharge per IEC61000-4-2.	10kV
Peak Package Solder Reflow Temperature	
(40 second maximum exposure)	
Operating Temperature	40°C to +125°C
Storage Temperature Range	65°C to +150°C

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

PACKAGE PIN OUT DIN 1 6 DOUT to IC SM PACKAGE OUT TO A COUT TO BUS SM PACKAGE

(Top View)

RoHS / Pb-free 100% Matte Tin Lead Finish

THERMAL DATA

SM Plastic 6-Pin SC70

THERMAL RESISTANCE-JUNCTION TO CASE, θ_{JC} 119 °C/W
THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA} 122 °C/W

Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$.

The $\theta_{\rm JA}$ numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.

•	FUNCTIONAL PIN DESCRIPTION				
	Name Description				
	VBUS	Bus Voltage			
	DIN	Data In			
	GND	Ground			
	DOUT	Data Out			

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, the following specifications apply over the operating ambient temperature -40°C \leq T_A \leq +125°C except where otherwise noted.

Parameter	Symbol	Test Conditions	LX7203			Units
raiailletei	Symbol	Test Conditions	Min	Тур	Max	Ullits
Stand-Off Voltage	VR _{WM}				5.25	V
Breakdown Voltage	V_{BR}	IR = 1mA	6			V
Leakage Current	I_R	VRWM = 5.25V, T = 25°C			1	μA
Series Resistance (-15)	Rs	Each Line	13.5	15	16.5	Ω
Series Resistance (-22)	Rs	Each Line	19.8	22	24.2	Ω
Temperature Coefficient of Rs	T _{COEFF}	Each Line		200		ppm
Pull Up Resistance	R _{PU}	Each Line	1.35	1.5	1.65	KΩ
Capacitor	C _{EDGE}	Each Line		47		pF
Total Capacitance	Стот	Between I/O Pins and Ground, Each Device VR = 0V, f = 1MHz	54	60	66	pF



PRODUCTION DATA SHEET

APPLICATION CIRCUITS

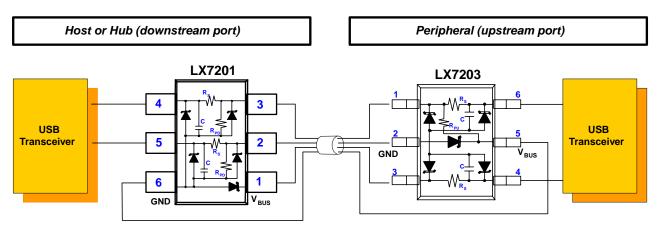


Figure 1 - Typical Application

APPLICATION INFORMATION

The LX7203 meets the requirements of the USB v1.1 and USB 2.0 Full Speed specification for device termination, EMI filtering and ESD protection. The $R_{\rm S}$ resistor provides the proper signal termination; the $C_{\rm EDGE}$ capacitor controls the signal rise and fall slew; the TVS diodes protect the IC from ESD damage; and the total capacitance and resistance creates a low pass filter eliminating the high frequency energy from the circuit. The LX7203 can configure the upstream port for either Full-Speed or Low-Speed operation. The figures below show the proper connection in accordance with the USB specification.

FULL SPEED DEVICE (FIGURE 2)

The USB 2.0 specification offers a 12 Mbps data transfer rate known as Full-Speed which requires a 1.5 k Ω pull-up resistor to be connected to the D+ line. Slew rate control is accomplished with C_{EDGE} attached to the transceiver before the R_S .

- Voltage Supply (Vbus) is connected to Pin 5
- Ground is connected to Pin 2
- D+ from the connector is routed to Pin 1 (1.5 kΩ pull-up resistor) and Pin 6 to the D+ line of the USB
 Transceiver
- D- from the connector is routed to Pin 3 and Pin 4 to the D- line of the USB Transceiver

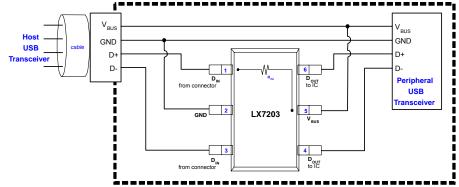


Figure 2 – Connection for Full Speed Operation



PRODUCTION DATA SHEET

APPLICATION INFORMATION (CONTINUED)

LOW SPEED DEVICE (FIGURE 3)

The USB v1.1 specification offers a 1.5 Mbps data transfer rate known as Low-Speed which requires a 1.5 $k\Omega$ pull-up resistor to be connected to the D- line. Slew rate control is accomplished with C_{EDGE} attached to the transceiver before the $R_{\rm S}.$

- Voltage Supply (Vbus) is connected to Pin 5
- Ground is connected to Pin 2
- D+ from the connector is routed to Pin 3 and Pin 4 to the D+ line of the USB Transceiver
- D- from the connector is routed to Pin 1 (1.5 kΩ pull-up resistor) and Pin 6 to the D- line of the USB Transceiver

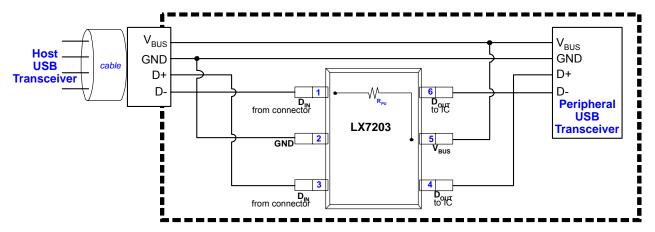


Figure 3 – Connection for Low Speed Operation

ELECTROMAGNETIC EMISSION AND SUSCEPTABILITY

FCC Part 15 sets limits for maximum allowable EM emission and susceptibility. There are two types of emissions. Conducted emissions with frequency of emission of 0.45 to 30 MHz and radiated emissions with frequency of emission of 30 MHz to 40 GHz. All digital computing devices including the peripheral devices must comply. Examples of peripheral devices include terminals, printers, external floppy disk drives and other data storage

devices, video monitors, keyboards, control cards, interface boards, external memory expansion cards and other input/output devices that may or may not contain digital circuitry. LX7203 is optimized to minimize the radiated EMI which is the primary concern in devices using USB. Refer to the typical filter response curve for the attenuation characteristics of LX7203 over the frequency range of 30kHz to 6GHz.



PRODUCTION DATA SHEET

CHARACTERISTIC CURVES

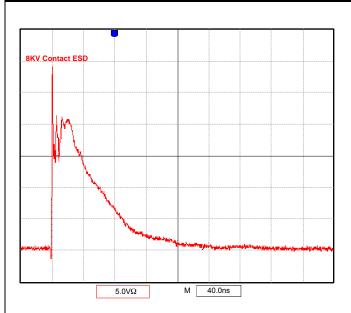


Figure 4 – 8KV ESD input pulse as per IEC61000-4-2. Vertical scale is equivalent to 5A/div.

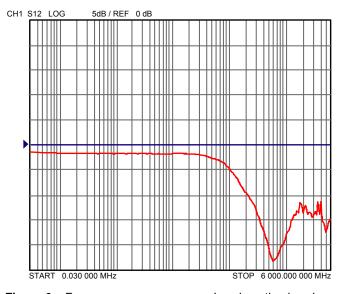


Figure 6 – Frequency response curve. Low insertion loss in the pass band and -20dB attenuation at 800-900 MHz. Better than -10dB attenuation at the WLAN frequencies of 2.4 and 5.0-6.0 GHz.

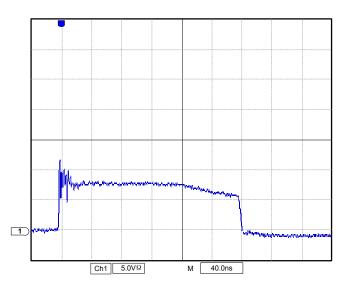


Figure 5 – Clamping Characteristics when device subjected to an 8 KV ESD pulse.

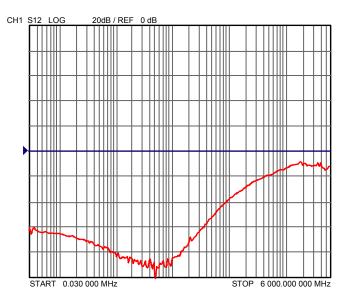


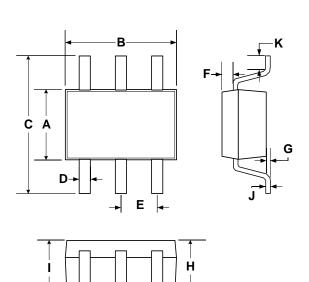
Figure 7 – Analog Crosstalk between the two datalines D-and D+



PRODUCTION DATA SHEET

PACKAGE DIMENSIONS

SMI 6 Pin Plastic SC70

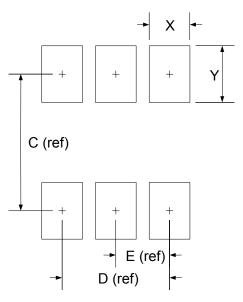


	MILLIMETERS		INCHES			
Dim	MIN	MAX	MIN	MAX		
Α	1.15	1.35	0.045	0.053		
В	1.80	2.20	0.071	0.086		
С	1.80	2.40	0.071	0.094		
D	0.15	0.30	0.006	0.012		
E	0.65	0.65 BSC		0.026 BSC		
F	0.10	0.40	0.004	0.016		
G	0	0.10	0	0.004		
Н	0.80	1.00	0.032	0.039		
I	0.80	1.10	0.032	0.043		
J	0.10	0.18	0.004	0.007		
K	0.10	0.30	0.004	0.012		

Note:

 Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side. Lead dimension shall not include solder coverage.

Recommended Footprint



	MILLIMETERS		INCHES		
Dim	MIN	MAX	MIN	MAX	
С	-	1.60	-	0.063	
D	-	1.30	-	0.052	
E	-	0.65	-	0.026	
Х	-	0.35	-	0.014	
Υ	_	0.90	_	0.035	



LX7203-xx

EMI Filter & ESD Protection for Up Stream USB Ports

PRODUCTION DATA SHEET

NOTES

PRODUCTION DATA – Information contained in this document is proprietary to Microsemi and is current as of publication date. This document may not be modified in any way without the express written consent of Microsemi. Product processing does not necessarily include testing of all parameters. Microsemi reserves the right to change the configuration and performance of the product and to discontinue product at any time.